



## N and P-Channel Enhancement Mode Power MOSFET

### Description

The NCE4503S uses advanced trench technology to provide excellent  $R_{DS(ON)}$  and low gate charge . The SOP-8 package is universally preferred for all commercial industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

## **General Features**

#### N-Channel

 $V_{DS} = 30V, I_D = 10A$  $R_{DS(ON)} < 20m\Omega @ V_{GS} = 4.5V$  $R_{DS(ON)} < 13.5m\Omega @ V_{GS} = 10V$ 

#### • P-Channel

 $V_{DS} = -30V, I_D = -9.1A$  $R_{DS(ON)} < 35m\Omega @ V_{GS} = -4.5V$  $R_{DS(ON)} < 20m\Omega @ V_{GS} = -10V$ 

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

## Application

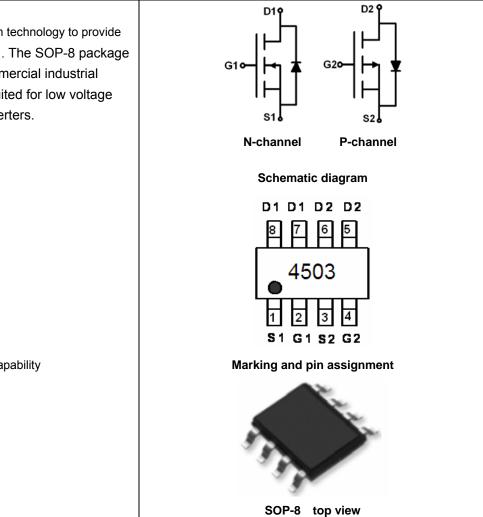
- Battery protection
- Load switch
- Power management

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
4503	NCE4503S	SOP-8	Ø330mm	12mm	2500 units

## Absolute Maximum Ratings (T<sub>A</sub>=25℃ unless otherwise noted)

Parame	Symbol	N-Channel	P-Channel	Unit		
Drain-Source Voltage		V <sub>DS</sub>	30	-30	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	±20	V	
Orationana Davia Oracat	T <sub>A</sub> =25℃		10	-9.1	٨	
Continuous Drain Current	T <sub>A</sub> =70℃	I <sub>D</sub>	7.9	-7.2	A	
Pulsed Drain Current (Note 1)		I <sub>DM</sub>	30	-30	А	
Maximum Power Dissipation T <sub>A</sub> =25°C		PD	2.5	2.5	W	
Operating Junction and Storage Te	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 150	-55 To 150	°C		









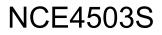
# Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note2)	<b>D</b> <sub>2</sub>	N-Ch	50	°C/W	
	R <sub>0JA</sub>	P-Ch	50	0.100	

## N-CH Electrical Characteristics (T<sub>A</sub>=25<sup>°</sup>C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	· · ·		·			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	BV <sub>DSS</sub> V <sub>GS</sub> =0V I <sub>D</sub> =250µA		33	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	I <sub>GSS</sub> V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V		-	±100	nA
On Characteristics (Note 3)	· · ·		•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1	1.6	3	V
Drain-Source On-State Resistance	Р	$V_{GS}$ =10V, $I_{D}$ =10A	-	7.5	13.5	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	-	11	20	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =5V,I <sub>D</sub> =10A	15	-	-	S
Dynamic Characteristics (Note4)	· · ·		•			
Input Capacitance	C <sub>lss</sub>		-	1550	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V, F=1.0MHz	-	300	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	180	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>		-	30	-	nS
Turn-on Rise Time	tr	$V_{DD}=25V,I_{D}=1A$	-	20	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10V, $R_{GEN}$ =6 $\Omega$	-	100	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	80	-	nS
Total Gate Charge	Qg		-	13	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =15V,I <sub>D</sub> =10A,	-	5.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =4.5V	-	3.5	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =6A	-	0.8	1.2	V





## P-CH Electrical Characteristics (T<sub>A</sub>=25<sup>°</sup>C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250µA	-30	-33	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-30V,V <sub>GS</sub> =0V	-	-	-1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	±100	nA
On Characteristics (Note 3)	·			•		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=-250\mu A$	-1	-1.5	-3	V
Drain Course On State Desistance	D	V <sub>GS</sub> =-10V, I <sub>D</sub> =-9.1A	-	15	20	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	$V_{GS}$ =-4.5V, I <sub>D</sub> =-5A	-	21	35	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =-15V,I <sub>D</sub> =-9.1A	10	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>		-	1600	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =-15V,V <sub>GS</sub> =0V, F=1.0MHz	-	350	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	300	-	PF
Switching Characteristics (Note 4)	· · · · ·					<u></u>
Turn-on Delay Time	t <sub>d(on)</sub>		-	10	-	nS
Turn-on Rise Time	tr	V <sub>DD</sub> =-15V, ID=-1A,	-	15	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =-10V, $R_{GEN}$ =6 $\Omega$	-	110	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	70	-	nS
Total Gate Charge	Qg	(1 - 45)(1 - 0.4)	-	30	-	nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =-15V,I <sub>D</sub> =-9.1A V <sub>GS</sub> =-10V	-	5.5	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> 10V	-	8	-	nC
Drain-Source Diode Characteristics	····					
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-6A	-	-	-1.2	V

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

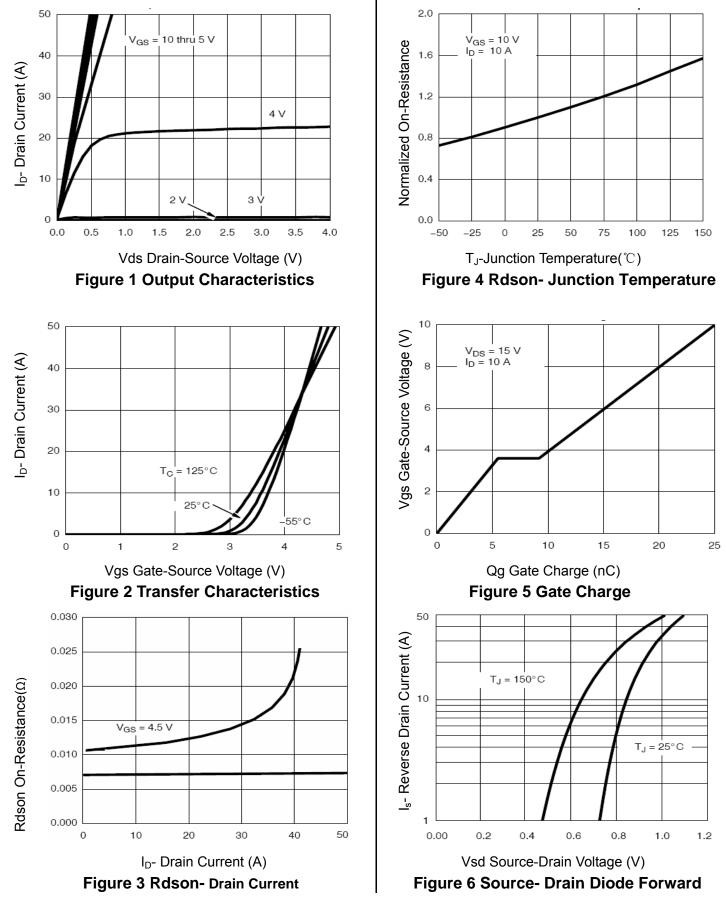
**2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.

- **3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production



NCE4503S

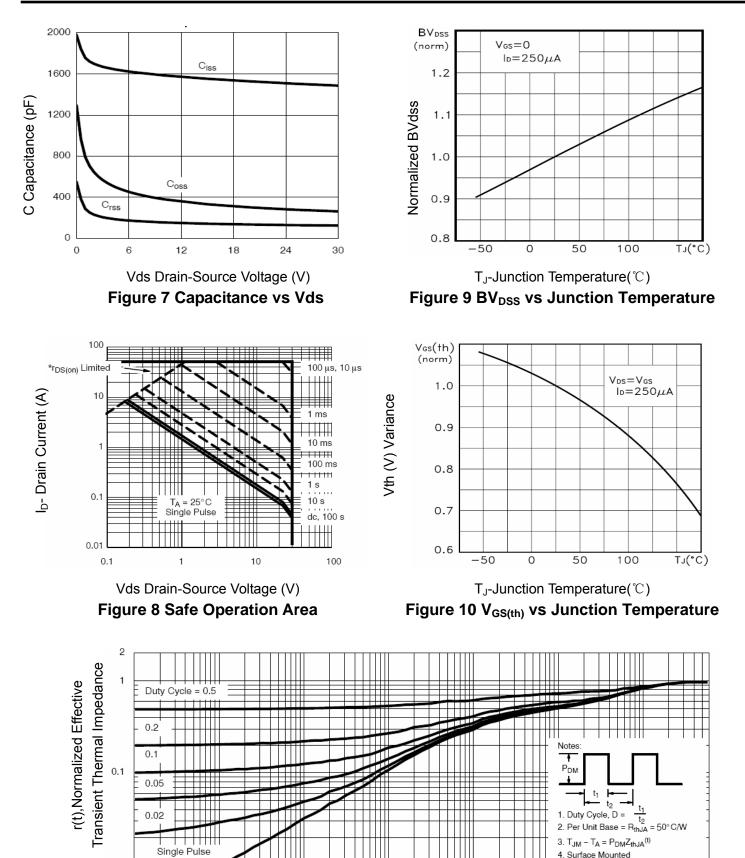
## N- Channel Typical Electrical and Thermal Characteristics (Curves)







NCE4503S





0.01





## **P-Channel Typical Electrical and Thermal Characteristics**

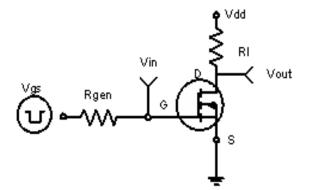
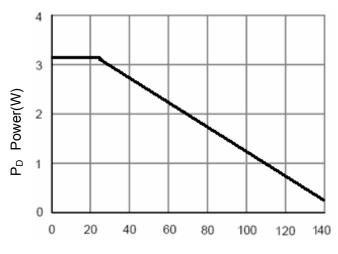
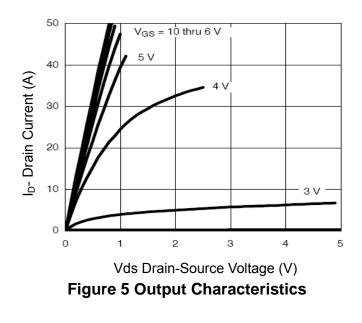
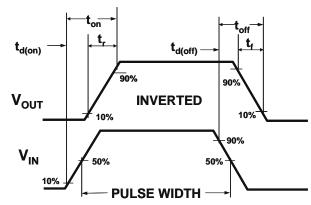


Figure 1:Switching Test Circuit

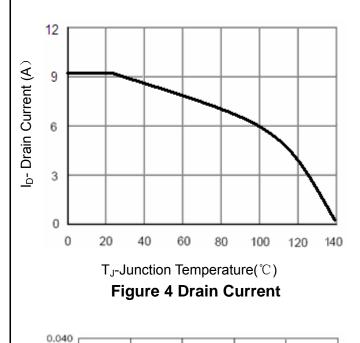


T<sub>J</sub>-Junction Temperature(℃) **Figure 3 Power Dissipation** 









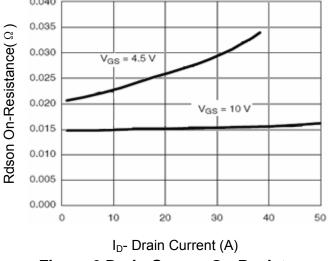
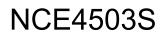
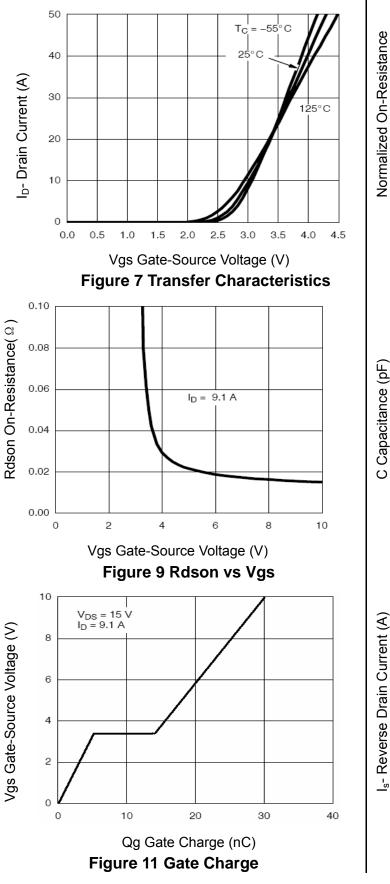


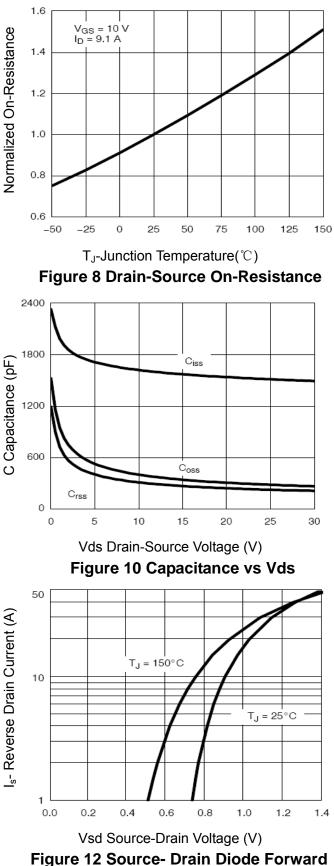
Figure 6 Drain-Source On-Resistance







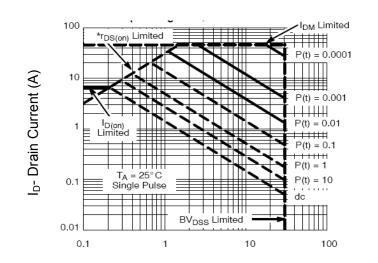












Vds Drain-Source Voltage (V)



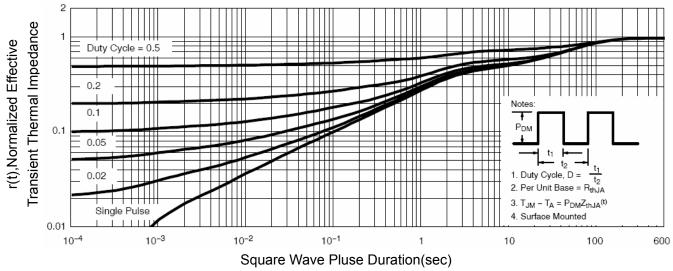


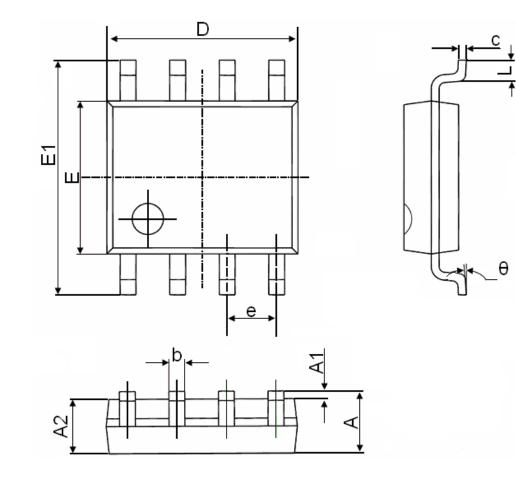
Figure 14 Normalized Maximum Transient Thermal Impedance







# SOP-8 Package Information



Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
С	0.170	0.250	0.006	0.010	
D	4.700	5.100	0.185	0.200	
E	3.800	4.000	0.150	0.157	
E1	5.800	6.200	0.228	0.244	
е	1.270	(BSC)	0.050(BSC)		
L	0.400	1.270	0.016	0.050	
θ	0°	8°	0°	8°	







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